

# RCJ200N20

# Nch 200V 20A Power MOSFET

$V_{DSS}$	200V
R <sub>DS(on)</sub> (Max.)	130m $Ω$
I <sub>D</sub>	±20A
$P_D$	106W

# ● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

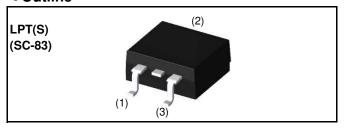
# Application

Switching Power Supply

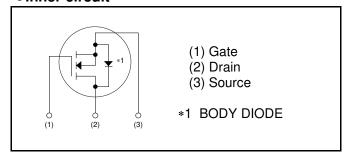
**Automotive Motor Drive** 

Automotive Solenoid Drive

#### Outline



## •Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	24
Туре	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ200N20

• Absolute maximum ratings( $T_a = 25$ °C)

Parameter		Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	200	V	
Continuous dusin suurent	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±20	А
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±10.9	А
Pulsed drain current		I <sub>D,pulse</sub> *2	±80	А
Gate - Source voltage		V <sub>GSS</sub>	±30	V
Avalanche energy, single puls	e	E <sub>AS</sub> *3	32.3	mJ
Avalanche current		I <sub>AR</sub> *3	10	А
$T_c = 25^{\circ}C$		P <sub>D</sub>	106	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P <sub>D</sub>	1.56	W
Junction temperature		T <sub>j</sub>	150	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.17	°C/W
Thermal resistance, junction - ambient *4	$R_{thJA}$	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# • Electrical characteristics $(T_a = 25^{\circ}C)$

Parameter	Symbol	Conditions	Values			Unit	
rarameter 	Syllibol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	200	-	-	V	
		$V_{DS} = 200V, V_{GS} = 0V$			25		
Zara gata valtaga drain aurrant	,	$T_j = 25^{\circ}C$	-	-	25	μΑ	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 200V, V_{GS} = 0V$	-	-	100		
		T <sub>j</sub> = 125°C					
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, \ V_{DS} = 0V$	-	ı	±100	nA	
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V$ , $I_D = 1mA$	3.0	ı	5.0	V	
		$V_{GS} = 10V, I_D = 10A$	-	100	130		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_D = 10A$		220	310	mΩ	
		T <sub>j</sub> = 125°C	_	220	310		
Forward transfer admittance	$g_{fs}$	$V_{DS} = 10V, I_{D} = 10A$	4.9	9.8	-	S	

# • Electrical characteristics $(T_a = 25^{\circ}C)$

Parameter	Symbol	Conditions	Values			Unit
r arameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	ı	1900	ı	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	120	1	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	70	1	
Turn - on delay time	$t_{d(on)}$ *5	$V_{DD} \simeq 100V, V_{GS} = 10V$	-	35	1	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 10A	-	100	1	ne
Turn - off delay time	$t_{d(off)}$ *5	$R_L = 10\Omega$	-	60	-	ns
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	45	-	

# • Gate Charge characteristics ( $T_a = 25$ °C)

Parameter	Cymbol	Conditions	Values			Unit
- rarameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*5}$	$V_{DD} \simeq 100V$	-	40	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 10A	-	15	-	nC
Gate - Drain charge	${\sf Q_{gd}}^{*5}$	$V_{GS} = 10V$	-	15	1	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 100V, I_D = 10A$	-	8.0	-	V

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
- Farameter	Syllibol	Symbol Conditions -		Тур.	Max.	Offic	
Continuous source current	l <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	ı	20	Α	
Pulsed source current	I <sub>SM</sub> *2	1 c = 23 0	-	-	80	Α	
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 10A	-	100	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	350	-	nC	

<sup>\*1</sup> Limited only by maximum temperature allowed.

\*5 Pulsed

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\simeq}$  500 $\mu$ H,  $V_{DD}$  = 50V, Rg = 25 $\Omega$ , starting  $T_j$  = 25°C

<sup>\*4</sup> Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

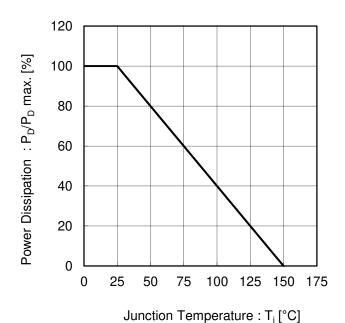
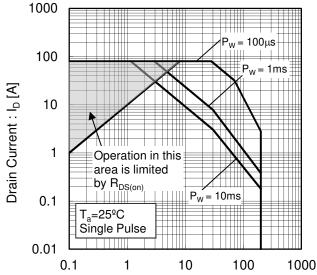
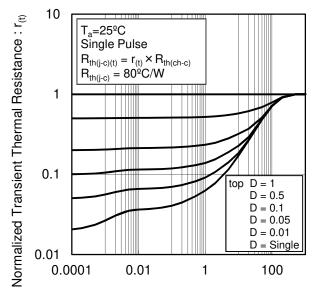


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw[s]

Fig.4 Avalanche Current vs Inductive Load

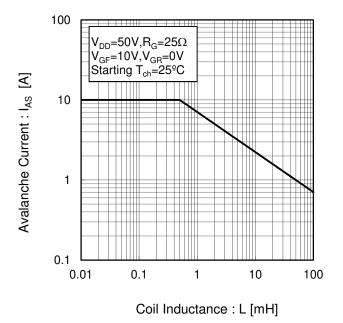
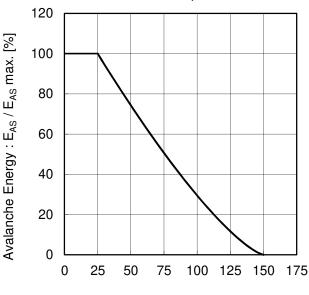


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



Junction Temperature : T<sub>i</sub> [°C]

Fig.6 Typical Output Characteristics(I)

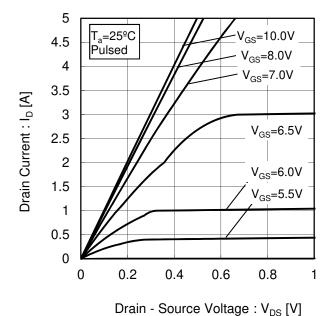
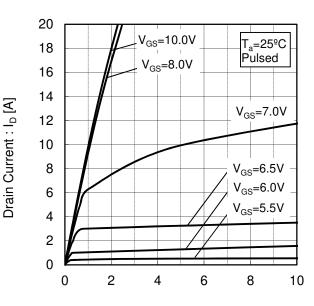


Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V<sub>DS</sub> [V]

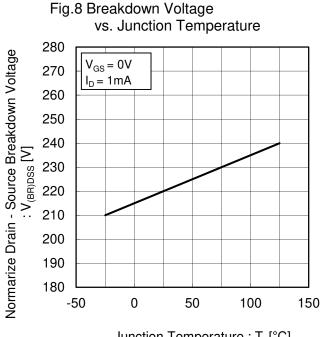
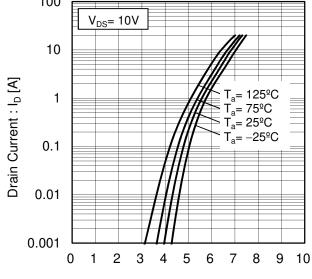


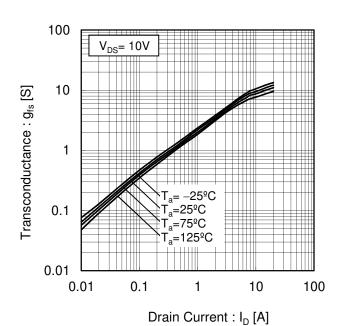
Fig.9 Typical Transfer Characteristics 100 **V**<sub>DS</sub>= 10**V** 10



Junction Temperature : T<sub>i</sub> [°C] Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature 5.0  $V_{DS} = 10V$  $I_D = 1 \text{mA}$ Gate Threshold Voltage: VGS(th) [V] 4.5 4.0 3.5 3.0 2.5 -50 -25 0 25 50 75 100 125 150 Junction Temperature : T<sub>i</sub> [°C]

Fig.11 Transconductance vs. Drain Current



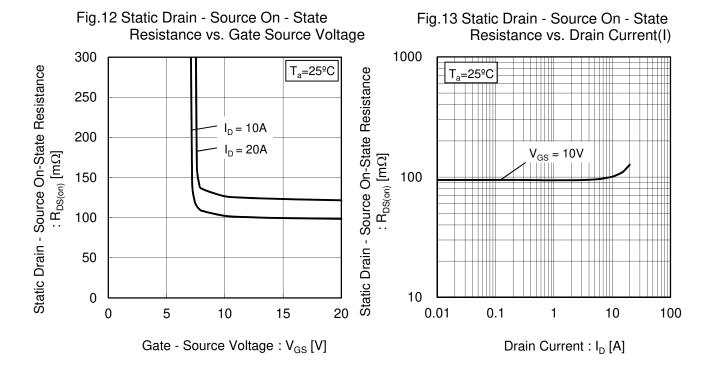


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature 300 Static Drain - Source On-State Resistance  $V_{GS} = 10V$  $I_D = 10A$ 250 200  $:R_{DS(on)}\left[ m\Omega \right]$ 150 100 50 0 -50 0 50 100 150 Junction Temperature :  $T_j$  [ ${}^{\circ}C$ ]

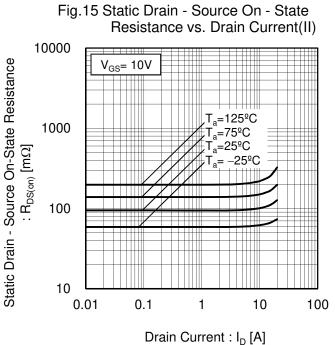


Fig.16 Drain Current Derating Curve

120
100
80
(%)
60
40
20
0
25 50 75 100 125 150 175

Junction Temperature :  $T_i$  [ ${}^{\circ}C$ ]

Fig.17 Typical Capacitance vs. Drain - Source Voltage 10000  $C_{iss}$ 1000 Capacitance: C [pF] 100  $\mathsf{C}_{\mathsf{rss}}$ 10 = 25°C 1MHz = 0V 0.1 0.01 10 100 1000

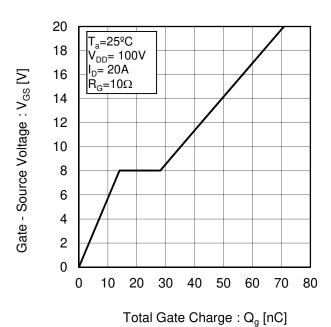
10000  $t_{r}$ 1000  $t_{r}$ 

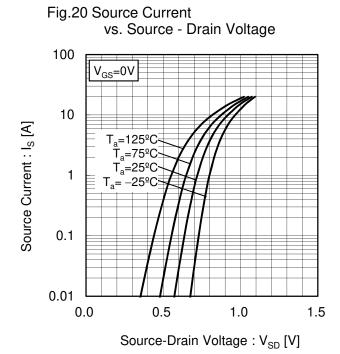
Drain Current : I<sub>D</sub> [A]

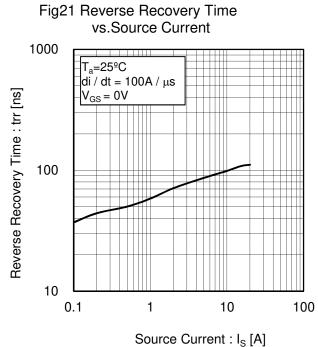
Fig.18 Switching Characteristics

Fig.19 Dynamic Input Characteristics

Drain - Source Voltage : V<sub>DS</sub> [V]







## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

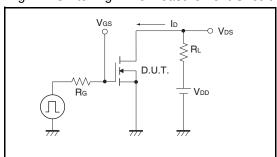


Fig.2-1 Gate Charge Measurement Circuit

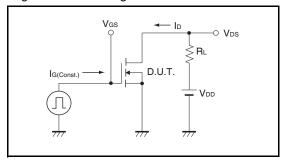


Fig.3-1 Avalanche Measurement Circuit

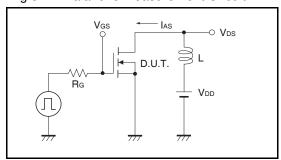


Fig.1-2 Switching Waveforms

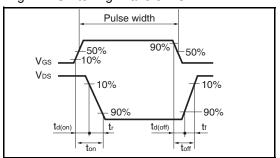


Fig.2-2 Gate Charge Waveform

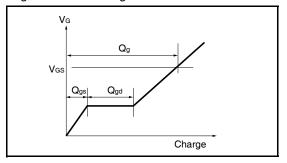
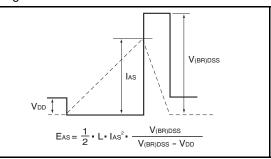
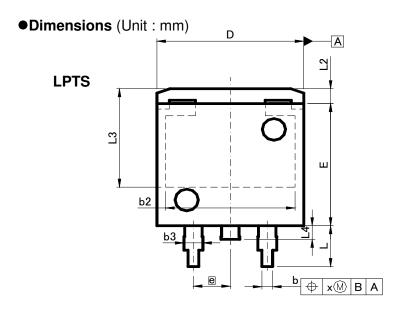
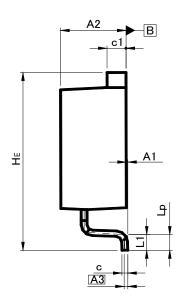
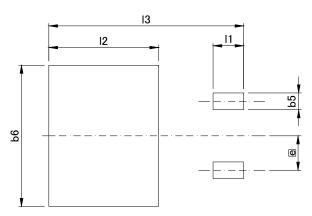


Fig.3-2 Avalanche Waveform









# Patterm of terminal position areas

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.	01
b	0.68	0.98	0.027	0.039
b2	8.	90	0.	35
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.10	
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.13
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.0	)43
L3	7.	7.25		185
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.01

DIM MILIME		ETERS	INC	INCHES	
DIM	MIN	MAX	MIN	MAX	
b5	ı	1.23	ı	0.049	
b6	-	10.40	-	0.409	
11	-	2.10	-	0.083	
12	=	7.55	_	0.297	
13	-	13.40	_	0.528	

Dimension in mm/inches

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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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